

Title (en)

ELECTROLESS COPPER PLATING BATH AND PLATING METHOD USING SUCH BATH

Publication

EP 0164580 B1 19890920 (EN)

Application

EP 85105723 A 19850510

Priority

US 61127884 A 19840517

Abstract (en)

[origin: EP0164580A2] The electroless copper plating bath having improved stability contains a cationic polymer from acrylamide and/or methacrylamide. The plating bath also contains essentially a cupric ion source, a reducing agent for the cupric ion source, and a complexing agent for the cupric ion. A substrate to be plated is contacted with the plating bath maintained preferably at a temperature in the range between about 70 DEG C and about 80 DEG C.

IPC 1-7

C23C 18/40

IPC 8 full level

C23C 18/40 (2006.01)

CPC (source: EP)

C23C 18/40 (2013.01)

Cited by

US4834796A; AU579776B2; EP0221265A1; US5039338A; CN100462480C; US5965211A; US4814009A; EP1681371B1

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